
Metode za preskušanje vzdržljivosti materialov za bondiranje čipov – 2. del:
Metoda s preskusom temperaturnega cikliranja materialov za bondiranje čipov,
uporabljenih za diskretne močnostne elektronske elemente

Endurance test methods for die attach materials - Part 2: Temperature cycling test
method for die attach materials applied to discrete type power electronic devices

Verfahren für die Haltbarkeitsprüfung von Werkstoffen zum Chip-Bonden - Teil 2:
Verfahren für die Temperaturwechselprüfung von Werkstoffen zum Chip-Bonden von
leistungselektronischen Bauelementen

Méthodes d'essai d'endurance pour les matériaux de fixation de puce - Partie 2:
Méthode d'essai de cycle thermique pour les matériaux de fixation de puce, appliquée
aux dispositifs électroniques de puissance de type discret

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**Endurance test methods for die attach materials - Part 2:
Temperature cycling test method for die attach materials applied
to discrete type power electronic devices
(IEC 63215-2:2023)**

Méthodes d'essai d'endurance pour les matériaux de
fixation de puce - Partie 2: Méthode d'essai de cycle
thermique pour les matériaux de fixation de puce, appliquée
aux dispositifs électroniques de puissance de type discret
(IEC 63215-2:2023)

Verfahren für die Haltbarkeitsprüfung von Werkstoffen zum
Chip-Bonden - Teil 2: Verfahren für die
Temperaturwechselprüfung von Werkstoffen zum Chip-
Bonden von leistungselektronischen Bauelementen
(IEC 63215-2:2023)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

EN IEC 63215-2:2023 (E)**European foreword**

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The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2024-08-28
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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60068-2-14	-	Environmental testing - Part 2-14: Tests - Test N: Change of temperature	EN IEC 60068-2-14	-
IEC 60194-1	-	Printed boards design, manufacture and assembly - Vocabulary - Part 1: Common usage in printed board and electronic assembly technologies	-	-
IEC 60194-2	-	Printed boards design, manufacture and assembly - Vocabulary - Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies	-	-
IEC 60747-15	-	Semiconductor devices - Discrete devices - Part 15: Isolated power semiconductor devices	EN 60747-15	-

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

ENDURANCE TEST METHODS FOR DIE ATTACH MATERIALS –**Part 2: Temperature cycling test method for die attach materials applied to discrete type power electronic devices****FOREWORD**

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Draft	Report on voting
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Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.